

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SUBHASHIS NATH	03/16/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INFOSYS LIMITED
<b>Street Address:</b>	IP CELL, PLOT NO. 44, ELECTRONICS CITY
<b>Internal Address:</b>	HOSUR ROAD
<b>City:</b>	BANGALORE
<b>State/Country:</b>	INDIA
<b>Postal Code:</b>	560100
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15927707
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(585)270-2179
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	585 270 2127
<b>Email:</b>	heather.dodge@leclairryan.com
<b>Correspondent Name:</b>	LECLAIRRYAN PLLC
<b>Address Line 1:</b>	70 LINDEN OAKS, SUITE 210
<b>Address Line 4:</b>	ROCHESTER, NEW YORK 14625
<b>ATTORNEY DOCKET NUMBER:</b>	29594.1800
<b>NAME OF SUBMITTER:</b>	HEATHER J. DODGE
<b>SIGNATURE:</b>	/Heather J. Dodge/
<b>DATE SIGNED:</b>	03/22/2018
<b>Total Attachments: 1</b>	
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### COMBINED DECLARATION AND ASSIGNMENT

I, Subhashis Nath ("ASSIGNOR(S)"), believe that I am the original inventor of a claimed invention in the following application(s) for which a patent is sought ("APPLICATIONS"):

U.S. Patent Application entitled METHOD AND SYSTEM FOR DATA ANALYSIS USING A STATISTICAL MODEL IN ONE OR MORE CONTEXTS hereby authorizes and requests the legal representatives of LeClairRyan, a Professional Corporation, 70 Linden Oaks, Suite 210, Rochester, New York 14625, who are associated with customer number 11951, to insert here in parenthesis (U.S. Application No. 15/927,707, filed on March 21, 2018) the Application's U.S. application number and filing date when known; and

India Patent Application No. 201741045674 filed on 19-Dec-2017;

I hereby declare that the above-identified application(s) were made or authorized to be made by me.

I hereby state that I have reviewed and understood the contents of the above-identified specification(s), including the claims. I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment of not more than five (5) years, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Infosys Limited, a company organized under the laws of the country of India, on behalf of itself and its successors and assigns ("ASSIGNEE"), is entitled to and is desirous of acquiring the entire and exclusive rights, title, and interest in the APPLICATIONS, and all other applications and patents derived therefrom, such as continuing applications, in and for the United States, its territories, and all foreign countries ("APPLICATION DERIVATIVES");

For good and valuable consideration, the receipt of which is hereby acknowledged by the ASSIGNOR(S), the ASSIGNOR(S) hereby sells, assigns, and transfers to the ASSIGNEE, the entire and exclusive rights, title, and interest in the APPLICATIONS, and APPLICATION DERIVATIVES, including foreign priority rights;

ASSIGNOR(S) agrees to sign any documents required for the prosecution of the APPLICATIONS and APPLICATION DERIVATIVES, for litigation regarding letters patent derived therefrom, and for protecting and perfecting title to the APPLICATIONS and APPLICATION DERIVATIVES.

  
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Inventor's Signature  
(Subhashis Nath)

Infosys Combined Declaration and Assignment\_nath\_self service analytics

16 Mar 2018  
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Date Inventor Signed